

# N-Channel 30-V (D-S) MOSFET

PRODUC	CT SUMMARY		
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)
30	0.030 at V <sub>GS</sub> = 10 V	6.5	4.5 nC
30	$0.033$ at $V_{GS} = 4.5 \text{ V}$	6.0	4.5110

## **FEATURES**

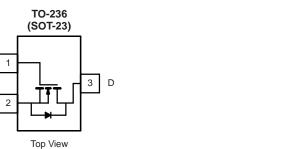
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC

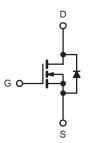


HALOGEN FREE

#### **APPLICATIONS**

DC/DC Converter





N-Channel MOSFET

ABSOLUTE MAXIMUM RATING	<b>GS</b> $T_A = 25  ^{\circ}C$ ,	unless othe	erwise noted		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	$V_{DS}$	30	V		
Gate-Source Voltage		$V_{GS}$	± 20	v	
	T <sub>C</sub> = 25 °C		6.5 <sup>a</sup>		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 70 °C	I <sub>D</sub>	6.0		
Continuous Brain Current (1) = 100 O)	T <sub>A</sub> = 25 °C	5 °C 5.3	5.3		
	T <sub>A</sub> = 70 °C	5.0	Α		
Pulsed Drain Current		I <sub>DM</sub>	25		
	T <sub>C</sub> = 25 °C		1.4		

	1A - 70 0		3.0	
Pulsed Drain Current		I <sub>DM</sub>	25	
	T <sub>C</sub> = 25 °C		1.4	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	Is	0.9 <sup>b, c</sup>	
	T <sub>C</sub> = 25 °C		1.7	
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	P <sub>D</sub>	1.1	w
Maximum rower bissipation	T <sub>A</sub> = 25 °C	۱ ۵ ا	1.1 <sup>b, c</sup>	VV
	T <sub>A</sub> = 70 °C		0.7 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C
Soldering Recommendations (Peak Temperature) <sup>d, e</sup>			260	C

THERMAL RESISTANCE RAT	NGS				
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	$R_{thJA}$	90	115	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	60	75	0/11

a. Package limited

- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 130 °C/W.



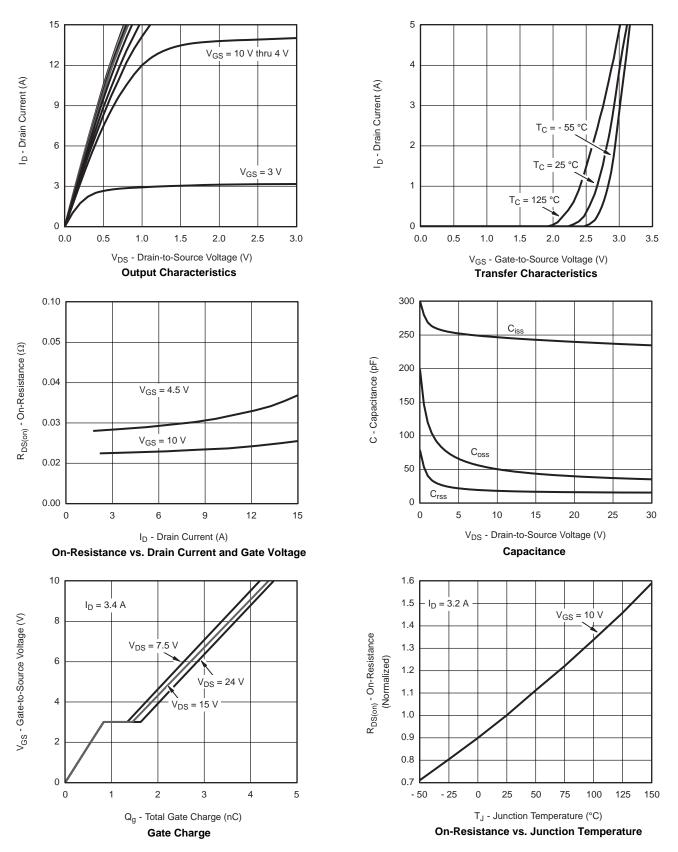
<b>SPECIFICATIONS</b> $T_J = 25  ^{\circ}C$ ,				1	ı		
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	30			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		31		m\//º(	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$			- 5		11107	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	0.7	1.1	2.0	V	
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	l	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	^	
Zero Gate voltage Drain Current	DSS	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α	
D : 0	D	$V_{GS} = 10 \text{ V, I}_{D} = 3.2 \text{ A}$		0.030			
Drain-Source On-State Resistance <sup>a</sup>	NDS(on)	$V_{GS} = 4.5 \text{ V}, I_D = 2.8 \text{ A}$		0.033		12	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_D = 4.8 \text{ A}$		11		S	
Dynamic <sup>b</sup>				1			
Input Capacitance	C <sub>iss</sub>			335			
Output Capacitance		$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		45		V mV/°C V nA μA A	pF
Reverse Transfer Capacitance		rss		17		1	
Total Oats Observe		$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 3.4 \text{ A}$		4.5	6.7		
Total Gate Charge	e Charge Q <sub>g</sub> V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3.4 X			2.1	3.2	1	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 3.4 \text{ A}$		0.85		nC	
Gate-Drain Charge	$Q_{gd}$			0.65			
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.8	4.4	8.8	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			12	20		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 5.6 $\Omega$		50	75		
Turn-Off Delay Time	$R_{DS(on)} = \frac{V_{GS} = 10 \text{ V, } I_{D} = 3.2 \text{ A}}{V_{GS} = 4.5 \text{ V, } I_{D} = 2.8 \text{ A}}$ $Q_{fS} = \frac{V_{DS} = 15 \text{ V, } I_{D} = 4.8 \text{ A}}{V_{DS} = 15 \text{ V, } I_{D} = 4.8 \text{ A}}$ $C_{iss} = \frac{V_{DS} = 15 \text{ V, } V_{GS} = 0 \text{ V, } f = 1 \text{ MHz}}{V_{DS} = 15 \text{ V, } I_{D} = 3.4 \text{ A}}$ $Q_{g} = \frac{V_{DS} = 15 \text{ V, } V_{GS} = 10 \text{ V, } I_{D} = 3.4 \text{ A}}{V_{DS} = 15 \text{ V, } V_{GS} = 4.5 \text{ V, } I_{D} = 3.4 \text{ A}}$ $Q_{gd} = \frac{V_{DS} = 15 \text{ V, } V_{GS} = 4.5 \text{ V, } I_{D} = 3.4 \text{ A}}{I_{D} = 15 \text{ V, } I_{D} = 3.4 \text{ A}}$ $Q_{gd} = \frac{V_{DS} = 15 \text{ V, } V_{GS} = 4.5 \text{ V, } I_{D} = 3.4 \text{ A}}{I_{D} = 2.7 \text{ A, } V_{GEN} = 4.5 \text{ V, } R_{g} = 1 \Omega}$ $Q_{gd} = \frac{V_{DD} = 15 \text{ V, } R_{L} = 5.6 \Omega}{I_{D} = 2.7 \text{ A, } V_{GEN} = 4.5 \text{ V, } R_{g} = 1 \Omega}$ $Q_{gd} = \frac{V_{DD} = 15 \text{ V, } R_{L} = 5.6 \Omega}{I_{D} = 2.7 \text{ A, } V_{GEN} = 10 \text{ V, } R_{g} = 1 \Omega}$ $Q_{gd} = \frac{V_{DD} = 15 \text{ V, } R_{L} = 5.6 \Omega}{I_{D} = 2.7 \text{ A, } V_{GEN} = 10 \text{ V, } R_{g} = 1 \Omega}$	12	20	1			
Fall Time	t <sub>f</sub>			22	35		
Turn-On Delay Time	t <sub>d(on)</sub>			5	10	ns	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 5.6 $\Omega$		12	20	1	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong$ 2.7 A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		10	15		
Fall Time				5	10	1	
<b>Drain-Source Body Diode Characteristi</b>	cs			L			
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			1.4	۸	
Pulse Diode Forward Current	I <sub>SM</sub>				15	^	
Body Diode Voltage	$V_{SD}$	$I_S = 2.7 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			10	20	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1 07 A 41/4 400 A/2 T 05 00		5	10	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 2.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		6			
Reverse Recovery Rise Time	t <sub>b</sub>			4		ns	

#### Notes:

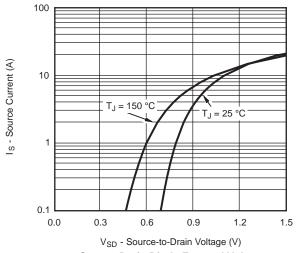
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing.

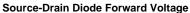
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

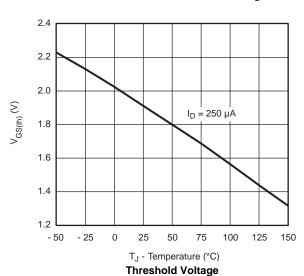




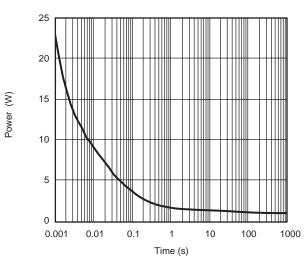




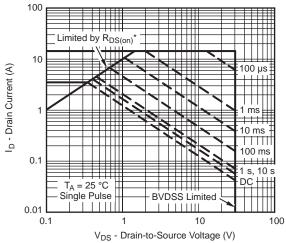




On-Resistance vs. Gate-to-Source Voltage



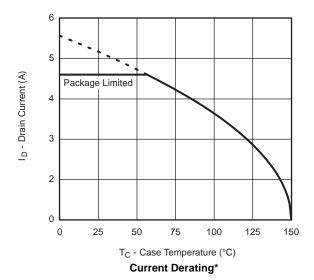
Single Pulse Power

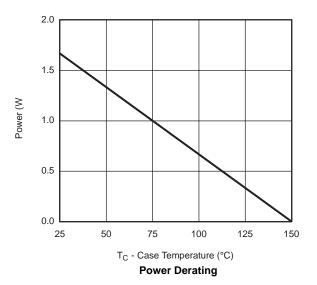


 $^{*}$  V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

Safe Operating Area, Junction-to-Ambient





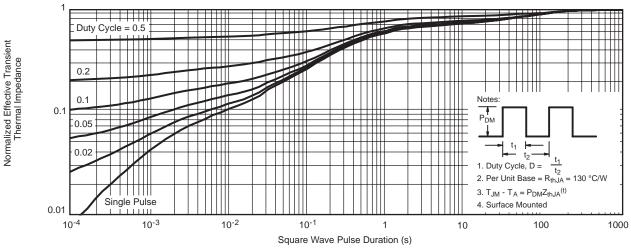


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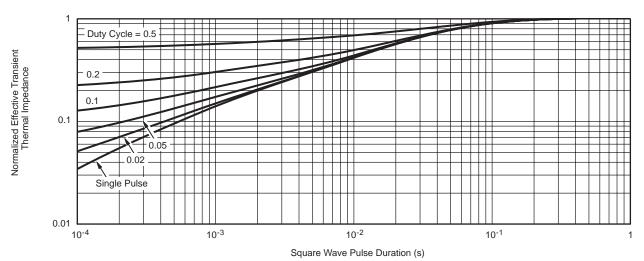
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<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





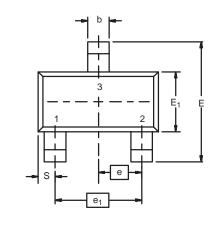
Normalized Thermal Transient Impedance, Junction-to-Ambient

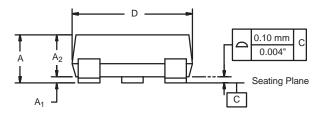


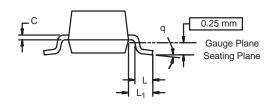
Normalized Thermal Transient Impedance, Junction-to-Foot



## SOT-23 (TO-236): 3-LEAD





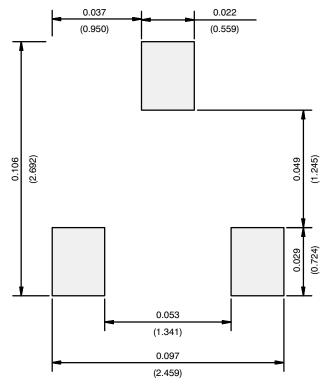


Dim	MILLIM	IETERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A <sub>1</sub>	0.01	0.10	0.0004	0.004	
A <sub>2</sub>	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E <sub>1</sub>	1.20	1.40	0.047	0.055	
е	0.95	BSC	0.0374 Ref		
e <sub>1</sub>	1.90	BSC	0.074	8 Ref	
L	0.40	0.60	0.016	0.024	
L <sub>1</sub>	0.64	Ref	0.025 Ref		
S	0.50	Ref	0.020 Ref		
q	3°	8°	3°	8°	

DWG: 5479



## **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
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BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2
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